



### SURFACE MOUNT SWITCHING DIODE ARRAY

## Features

- Fast Switching Speed
- Small Surface Mount Package
- Low Leakage Current
- Two "BAV70" Circuits in One Package
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

## **Mechanical Data**

- Case: SOT-363
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020D
- Terminals: Matte Tin Finish Annealed over Alloy 42 Leadframe (Lead-Free Plating). Solderable per MIL-STD-202, Method 208<sup>(3)</sup>
- Orientation: See Diagram
- Weight: 0.006 grams (Approximate)



TOP VIEW SOT-363



TOP VIEW Internal Schematic

## Ordering Information (Note 4)

Part Number	Case	Packaging
BAV70DW-7-F	SOT-363	3000/Tape & Reel

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.

2. See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds1.

4. For packaging details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

## **Marking Information**

Notes:

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Date Code Key					/ \	KJA = Prod YM = Date Y = Year ex M = Month	Code Mark k: B = 2014	king I	de			
Year	2001	2002		2010	2011	2012	2013	2014	2015	2016	2017	2018
Code	М	N		Х	Y	Z	A	В	С	D	E	F
							Dee					
Month	Jan	Feb	Mar	Apr	Мау	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	Ν	D



# **Maximum Ratings** (@T<sub>A</sub> = +25°C unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Non-Repetitive Peak Reverse Voltage		V <sub>RM</sub>	100	V
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage		V <sub>RRM</sub> V <sub>RWM</sub> Vr	80	V
RMS Reverse Voltage		V <sub>R(RMS)</sub>	57	V
Forward Continuous Current (Note 5)		I <sub>FM</sub>	300	mA
Average Rectified Output Current (Note 5)		lo	150	mA
Repetitive Peak Forward Current		I <sub>FRM</sub>	450	mA
Non-repetitive Peak Forward Surge Current	@ t = 1.0µs @ t = 1.0ms @ t = 1.0s	IFSM	4 1 0.5	A

# **Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	PD	200	mW
Thermal Resistance, Junction to Ambient Air (Note 5)	$R_{ ext{ heta}JA}$	625	°C/W
Thermal Resistance, Junction to Solder Point	R <sub>0</sub> JSP	70	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-65 to +150	°C

## Electrical Characteristics (@T<sub>A</sub> = +25°C unless otherwise specified.)

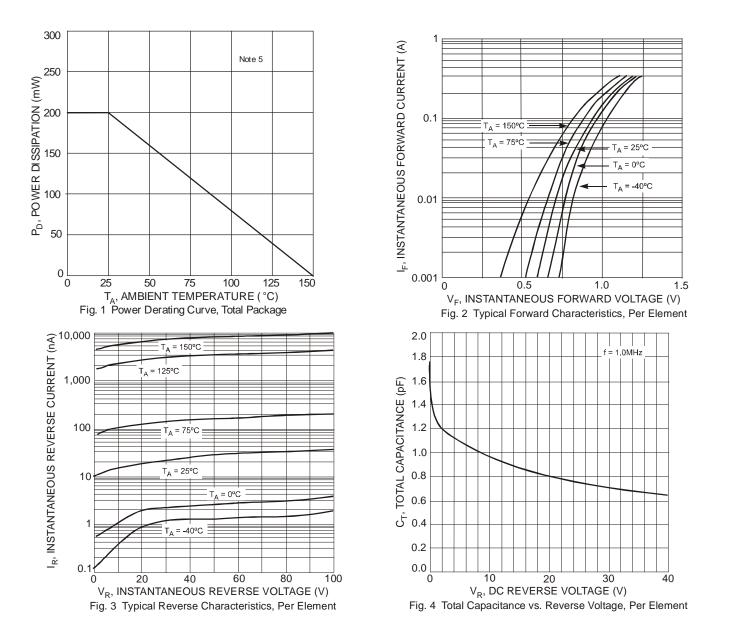
Characteristic	Symbol	Min	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 6)	V <sub>(BR)R</sub>	75 80	_	V	I <sub>F</sub> = 2.5μA I <sub>F</sub> = 20μA
Forward Voltage	VF	_	0.715 0.855 1.0 1.25	V	$I_{F} = 1.0mA$ $I_{F} = 10mA$ $I_{F} = 50mA$ $I_{F} = 150mA$
Reverse Current (Note 6)	I <sub>R</sub>	_	2.5 50 30 25	μΑ μΑ μΑ nA	$V_R = 75V$ $V_R = 75V$ , $T_J = +150^{\circ}C$ $V_R = 25V$ , $T_J = +150^{\circ}C$ $V_R = 20V$
Total Capacitance	CT	_	1.5	pF	V <sub>R</sub> = 0, f = 1.0MHz
Reverse Recovery Time	t <sub>rr</sub>	_	4.0	ns	$I_{F} = I_{R} = 10 \text{mA},$ $I_{rr} = 0.1 \text{ x } I_{R}, R_{L} = 100 \Omega$
Forward Recovery Voltage	V <sub>FR</sub>	_	1.75	V	$I_F = 10 \text{mA}, t_r = 20 \text{ ns}$

Notes: 5. Device mounted on FR-4 PCB, 1in. x 0.85in. x 0.062in. Pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf.

Short duration pulse test used to minimize self-heating effect.

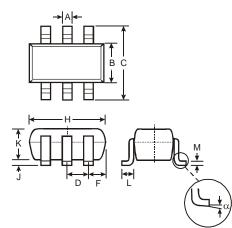


# BAV70DW



## **Package Outline Dimensions**

Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



Dim	Min	Max	Тур				
Α	0.10	0.30	0.25				
В	1.15	1.35	1.30				
С	2.00	2.20	2.10				
D	0.65 Typ						
F	0.40	0.45	0.425				
Н	1.80	2.20	2.15				
J	0	0.10	0.05				
κ	0.90	1.00	1.00				
L	0.25	0.40	0.30				
М	0.10	0.22	0.11				
α	0°	8°	-				
All Dimensions in mm							

SOT363

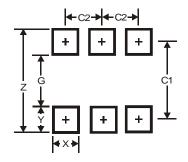
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## Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
Z	2.5
G	1.3
Х	0.42
Y	0.6
C1	1.9
C2	0.65

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